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Socionext to Showcase Advanced SoC Design Solutions at DesignCon 2019

Featuring High-Performance SoC, Ultra-High-Speed CMOS Transceivers, AI, and Advanced Packaging Technologies

Sunnyvale Calif., January 17, 2019 --- Socionext Inc., a world leading silicon supplier, will feature its advanced SoC designs including 112G SerDes, 120+ GS/s ADC/DAC, AI technology, high-performance memory, multi-die packaging and RF/mmWave solutions at the annual DesignCon conference, Jan. 30 – 31, at the Santa Clara Convention Center, Booth 1234.

To accommodate the exponentially growing data center traffic, cloud service providers require high-speed signaling for chip-to-module, chip-to-chip, and board-to-board communications. Socionext provides a high-performance SerDes macro with up to 112Gbps per channel for 100G/200G/400G networks. These capabilities are further extended by utilizing the company's ultra-high-speed ADC & DAC technologies, a key component in coherent and direct detect optical networking SoCs enabling Terabit (Tbps) datacenter interconnect (DCI) solutions for hyperscale cloud operators.

Socionext will demonstrate solutions of ultra-energy-efficient 56Gb/s PAM4 SR to LR CMOS transceivers optimized to help companies cost-effectively meet the ever-increasing demand for performance, functionality and design requirements.

The company will also showcase a high-performance, energy-efficient edge server with AI accelerator delivering powerful parallel processing performance for video processing and image recognition. This video management system is optimized for facial and object recognition ideal for surveillance and security applications.

With the adoption of AI applications within the cloud data center, there is an increasing demand for greater interconnect bandwidth, larger on-chip memory, and ultra-low latency. As a proven and trusted partner, Socionext provides extended HBM+, multi-die packaging, and advanced process node solutions for meeting and exceeding these emerging requirements.

The company will also showcase advanced "Chip-Package-PCB co-design" methodology developed to help companies quickly and cost-effectively deliver high-quality, high-performance, multi-die packaging and RF/mmWave solutions.

Socionext will be raffling great prizes at DesignCon, so stop by booth #1234 to learn more!

For the DesignCon website and programs, visit http://www.designcon.com/

About Socionext America Inc.

Socionext America, Inc. (SNA) is the US branch of Socionext Inc. headquartered in Sunnyvale, California. The company is one of the world's leading fabless ASIC suppliers, specializing in a wide range of standard and customizable SoC solutions for imaging, networking, computing and other dynamic applications. Socionext provides customers with quality semiconductor products based on extensive and differentiated IPs, proven design methodologies, and state-of-the-art implementation expertise, with full support.

For product information, visit our website, e-mail sna_inquiry@us.socionext.com or call 1-844-680-3453. For company news and updates, connect with us on Twitter, Facebook and YouTube.

About Socionext Inc.

Socionext is a global, innovative enterprise that designs, develops and delivers System-on-Chip based solutions to customers worldwide. The company is focused on imaging, networking, computing and other dynamic technologies that drive today's leading-edge applications. Socionext combines world-class expertise, experience, and an extensive IP portfolio to provide exceptional solutions and ensure a better quality of experience for customers. Founded in 2015, Socionext Inc. is headquartered in Yokohama, and has offices in Japan, Asia, United States and Europe to lead its product development and sales activities. For more information, visit www.socionext.com.